What is claimed is:

1. A vacuum lamination system, comprising

a batch type vacuum laminating device configured to laminate ~~in which~~ a laminate film and a laminate base item that is conveyed on a lower carrier film; ~~are laminated by a batch type vacuum laminating device,~~

a cutting device configured to cut ~~and~~ the laminate film ~~is cut~~ from the laminated item having the laminate film laminated thereon, wherein

the cutting device is configured to cut, in a state in which the laminated item having the laminate film laminated thereon is mounted on the lower carrier film, an excessive portion of the laminate film ~~is cut~~ from the laminated item having the laminate film laminated thereon.

2. The vacuum lamination system according to claim 1, wherein the laminate base item is a round-shape wafer and the laminate film is a continuous laminate film or a laminate film cut into a rectangle, and wherein the cutting device is further configured to cut the laminate film ~~is cut~~ in accordance with a shape of the laminated wafer.

3. The vacuum lamination system according to claim 1 or 2, wherein the cut-off excessive portion of the laminate film is arranged to be wound up together with the lower carrier film.

4. A vacuum lamination method comprising the steps of: laminating a laminate film and laminate base items that are conveyed on a lower carrier film by a batch type vacuum laminating device; and cutting the laminate film from the laminated item having the laminate film laminated thereon, wherein

in a state in which the laminated item having the laminate film laminated thereon is mounted on the lower carrier film,